

BANDPASS FILTER DESIGN USING PLANAR COUPLE MICROSTRIP LINES

NURUL ATIQAH BINTI ISMAIL

This Report Is Submitted In Partial Fulfillment Of The Requirement For The Award Of
Bachelor Of Electronic Engineering (Computer Engineering)
With Honours

Faculty of Electronic and Computer Engineering
Universiti Teknikal Malaysia Melaka

May 2011



UNIVERSITI TEKNIKAL MALAYSIA MELAKA
FAKULTI KEJURUTERAAN ELEKTRONIK DAN KEJURUTERAAN KOMPUTER

BORANG PENGESAHAN STATUS LAPORAN
PROJEK SARJANA MUDA II

Tajuk Projek : BANDPASS FILTER DESIGN USING PLANAR COUPLE
MICROSTRIP LINES
Sesi Pengajian : 2010/2011

Saya NURUL ATIQAH BINTI ISMAIL
mengaku membenarkan Laporan Projek Sarjana Muda ini disimpan di Perpustakaan dengan syarat-syarat kegunaan seperti berikut:

1. Laporan adalah hakmilik Universiti Teknikal Malaysia Melaka.
2. Perpustakaan dibenarkan membuat salinan untuk tujuan pengajian sahaja.
3. Perpustakaan dibenarkan membuat salinan laporan ini sebagai bahan pertukaran antara institusi pengajian tinggi.
4. Sila tandakan (\checkmark) :

SULIT*

(Mengandungi maklumat yang berdarjah keselamatan atau kepentingan Malaysia seperti yang termaktub di dalam AKTA RAHSIA RASMI 1972)

TERHAD*

(Mengandungi maklumat terhad yang telah ditentukan oleh organisasi/badan di mana penyelidikan dijalankan)

TIDAK TERHAD

Disahkan oleh:

(TANDATANGAN PENULIS)

Alamat Tetap: NO. 16, KG PAYA KECIL
BT.4, JLN MENTAKAB
28000 TEMERLOH
PAHANG DARUL MAKMUR

(COP DAN TANDATANGAN PENYELIA)

Tarikh : 3th MEI 2011

Tarikh: 3th MEI 2011

a

“I hereby declare that this report is the result of my own work except for quotes as cited in the references.”

Signature :.....
Author :.....
Date :.....

“I hereby declare that I have read this report and in my opinion this report is sufficient in terms of the scope and quality for the award of Bachelor of Electronic Engineering (Computer Engineering) With Honours.”

Signature :.....
Supervisor’s Name :.....
Date :.....

*Specially dedicated to my beloved parents
Ismail bin Taib and Siti Hasnah binti Ahmad,
brother, sisters and all my fellow friends
who have encouraged, guided and inspired me throughout my journey of education*

ACKNOWLEDGEMENT

In the name of Allah S.W.T, the most Merciful and the most Gracious

Alhamdulillah, a lot of thanks to Allah S.W.T for His blessing for me to complete my Final Year Project and this thesis is symbolic of the support and guidance that I get from all my family and friends.

First and foremost, I would like to express my heartily gratitude to my supervisor, Dr. Badrul Hisham bin Ahmad for the guidance and enthusiasm given throughout the progress of this project.

My appreciation also goes to my family who has been so tolerant and supports me all these years. Special thanks for their encouragement, love and emotional support that they had given to me.

I also would like to thank to those who has given the constructive comments and ideas in completing this project and I hope this project could give the advantages and knowledge for all the readers.

ABSTRACT

Filter is highly desirable in communication system. It functions to pass through the desired frequencies within the range and block unwanted frequencies. In addition, filters are also needed to remove out harmonics that are present in the communication system. The objective of this project is to design, construct and fabricate microstrip suitable with centered at 9GHz. The filter must operate within the unlicensed 9GHz band. This application is in the X band range (8-12GHz) currently being used for industrial, medical and scientific applications. A planar couple microstrip lines prototype filter was produced with the bandwidth is 1GHz. The filter covers the 9GHz band and the bandwidth from 8.5GHz to 9.5 GHz. The filter was fabricated on FR4 board, that had a relative dielectric constant, $\epsilon_r = 4.7$, a loss tangent $\tan \delta = 0.019$ and thickness, h of 1.6 mm.

ABSTRAK

Peranti penapis sangat diperlukan dalam sistem komunikasi. Ia berfungsi membenarkan satu julat frekuensi yang dikehendaki dan menghalang satu julat frekuensi yang tidak dikehendaki. Di samping itu, penapis juga diperlukan untuk membuang harmonik yang tidak dikehendaki dalam sistem komunikasi. Projek ini bertujuan untuk merekabentuk dan membina penapis jalurmikro yang boleh beroperasi dalam frekuensi 9GHz. Aplikasi ini didalam ukuran X band (8-12GHz), yg selalunya digunakan untuk industri, perubatan dan saintifik. Pasangan mikrostrip garis planar ini menghasilkan lebarjalur 1GHz iaitu dari frekuensi 8.5GHz sehingga 9.5GHz. Antenna tersebut dibina pada FR4 yang mempunyai $\epsilon_r = 4.7$, $\tan \delta = 0.019$ dan ketebalan, h of 1.6 mm.

TABLE OF CONTENTS

CHAPTER	CONTENT	PAGE
	DECLARATION	iii
	DEDICATION	iv
	ACKNOWLEDGEMENTS	vi
	ABSTRACT	vii
	ABSTRAK	viii
	TABLE OF CONTENTS	ix
	LIST OF TABLES	xii
	LIST OF FIGURES	xiii
	LIST OF ABBREVIATIONS	xv
	LIST OF APPENDIX	xvi
I	INTRODUCTION	
	1.1 Project Overview	1
	1.2 Problem Statement	2
	1.3 Objectives	2
	1.4 Scope	2
	1.5 Project Outline	3

II**LITERATURE REVIEW**

2.1	Introduction	4
2.2	Microstrip Line	4
2.2.1	Basic Microstrip Line	4
2.2.2	Microstrip Field Radiation	5
2.2.3	Substrate Materials	7
2.2.4	Applications	8
2.2.5	The Five Microstrip Filters Illustrate Are	9
2.2.6	Microstrip Couplers	10
2.2.7	The Comparison between Microstrip, Waveguide and Substrate Integrated Waveguide.	13
2.2.8	Comparison of Popular Transmission Media	13
2.3	Filter	14
2.3.1	Filter Circuits	14
2.3.2	Filters Technologies	17
2.4	Parallel-Coupled Filters	19
2.5	Filter Loss	21
2.5.1	Insertion Loss	21
2.5.2	Return Loss	21
2.6	Microwave Board	22

III**PROJECT METHADODOLOGY**

3.1	Introduction	23
3.2	Overview of Procedure	23
3.3	Project Flow Chart	24
3.3.1	Project Development	24
3.4	Design	26

	3.4.1	Simulation	26
	3.4.2	Fabrication	26
	3.4.3	Testing	27
IV		DESIGN PROCESS AND FABRICATION	
	4.1	Design Specification	28
	4.2	Calculation	29
	4.3	Simulation	35
	4.4	Fabrication	41
V		RESULT, ANALYSIS AND DISCUSSION	
	5.1	Introduction	47
	5.2	Result and Analysis	47
	5.3	Discussions	50
VI		CONCLUSION AND RECOMMENDATION	
	6.1	Conclusion	52
	6.2	Future Work	52

REFERENCES

LIST OF TABLES

TABLE NO.	TITLE	PAGE
2.2.7 (i)	The comparison between microstrip, waveguide and SIW	13
2.2.7 (ii)	Comparison of popular transmission media	13
2.6	Material specification for microwave board	22
4.1 (i)	Microstrip filter specifications	28
4.2 (ii)	Three equations above are used to obtain the J-inverters	32
4.2 (iii)	The result for Z_{oe} and Z_{os} after calculation	33
4.2 (iii)	The size for W, S and L	34
5.2 (i)	The size of W, S and L	49
5.2 (ii)	Summary of the implemented filters and the filter specification	50

LIST OF FIGURES

FIGURE NO.	TITLE	PAGE
2.2.1	Structure of Microstrip Configuration	5
2.2.2	Electromagnetic Field Pattern of a Microstrip	6
2.2.5	Types of microstrip filter	9
2.2.6 (i)	The parallel coupled microstrip in cross section	11
2.2.6 (ii)	The parallel coupled microstrip lines	11
2.2.6 (iii)	The field pattern for even and odd mode	12
2.3.1(i)	Schematic Reciprocal Two-Port Filtering Network	15
2.3.1(ii)	Low pass filter	16
2.3.1(iii)	Bandpass filter	16
2.3.1(iv)	High pass filter	17
2.4(i)	Illustrate a general structure of parallel-coupled (or edge-coupled)	20
2.4 (ii)	General structure of parallel (edge)-coupled microstrip bandpass filter	21
2.5.2	Example of insertion and return loss response	23
3.3	Project Flow Chart	24
3.3.1	Design process Flow Chart	25
4.2(i)	Fractional Bandwidth	29
4.2(ii)	Bandpass filter conversion	30
4.2(iii)	Coupled line filter configuration	30
4.2(iv)	Equivalent circuit of coupled U4 open lines	31

4.2(vi)	The LineCal in ADS software	34
4.3(i)	The new schematic	36
4.3 (ii)	The schematic design	36
4.3 (iii)	The plot traces and attributes	37
4.3 (iv)	The design is set in dB	37
4.3 (v)	The simulation result	38
4.3 (vi)	The printed circuit layout	38
4.3 (vii)	The port need to connect with the design	39
4.3(viii)	The substrate need to setup in FR4 specification	40
4.3 (ix)	The simulation control	40
4.4(i)	The print out design	41
4.4(ii)	The Ultraviolet process	42
4.4(iii)	The developer process	56
4.4(iv)	The dryer machine	56
4.4(v)T	he etching process	57
4.4(vi)	The fabricated design for N=3	59
4.4(vii)	The fabricated design for N=7	59
4.4(viii)	The network analyzer	59
4.4(ix)	The measure output for N=3	60
4.4(x)	The measure output for N=7	60

LIST OF ABBREVIATIONS

LPF	-	Lowpass filter
BPF	-	Bandpass filter
BSF	-	Bandstop filter
IL	-	Insertion loss
RT	-	Return loss
BW	-	Bandwidth
PCB	-	Printed circuit board
I/O	-	Input/output
Z_o	-	High impedance
Z_{oo}	-	Z odd
Z_{oe}	-	Z even
ADS	-	Advance design system
dB	-	Decibel
ϵ_r	-	Dielectric constant
h	-	Dielectric substrate
SIW	-	Substrate integrated waveguide
TEM	-	Transverse electromagnetic
NEMA	-	Nasional Electrical Manufacturers Association
FR	-	Fire resistant
HFSS	-	High Frequency Structure Simulator
N	-	Number of element

LIST OF APPENDICES

APPENDIX	TITLE	PAGE
A	Poster during seminar PSM 2	61
B	Gantt chart for PSM	62
C	Chebyshev filter coefficients; 0.5dB filter design (N=1 to10)	63

CHAPTER I

INTRODUCTION

1.1 Project Overview

This project will develop a bandpass filter using planar couple microstrip lines. Using Advance Design System (ADS) the planar couple will be design and then determine the best specs refer to simplicity in fabricating. The planar couple will be simulate, fabricate and tested.

Filters are essential in the RF front end of microwave wireless communication system. In planar microstrip and stripline realization, one of the most common implementation methods for bandpass and bandstop filters with required bandwidths up to a 40% of central frequency is to use a cascade of parallel coupled sections.

The synthesis procedure which consists of the design equation for the coupled line physical parameters (space-gap between parallel lines, line widths and lengths) is easy and can be found in any classical microwave books. Based on this, a well defined systematic procedure, for the required parallel coupled microstrip filter physical parameters can be easily derived for both Butterworth and Chebyshev response of any

order. The filter can be fabricated easily and it exhibits reasonably good performance compared with other planar circuit filters.

Although parallel coupled bandpass microstrip filter is very popular and simple, the traditional design does suffer from a fundamental limitation, namely, the presence of spurious response at twice the basic passbands at the design frequency.

1.2 Problem Statement

Microstrip is a cheaper, reliable and easy to connect with the other planar device. Compare to waveguide, microstrip is thus much less expensive than traditional waveguide technology, as well as being far lighter, Q high and more compact.

1.3 Objectives

The objectives of this project are:

- i. To design, develop and test a bandpass filter using microstrip planar couple lines.
- ii. To compare the result of couple line filter with rectangular waveguide bandpass filter and SIW

1.4 Scope

The scope of this project is to design microstrip parallel coupled bandpass filter using Advanced Design System (ADS) 2008 software, matching to 50Ω microstrip line parallel coupled and analysis of insertion loss and return loss using Chebyshev response characteristic with passband ripple of 0.5dB between the passband frequencies of

8.5GHz and 9.5GHz. The frequency is operate in X band range between 8GHz to 12GHz. This project will involve simulation and fabrication of microstrip bandpass filter. The design will be fabricate on FR4 board with dielectric constant is 4.7. After that it will be compare with regtangular waveguide bandpass and SIW bandpass filter.

1.5 Project Outline

This thesis comprises of six chapters. The first chapter briefly discusses the overviews about the project such as introduction, objectives, problem statements and scope of this project.

Chapter 2 describes about the research and information about the project. Every facts and information, which found through by any references had been selected. This literature review has been explained about the planar couple microstrip lines.

Chapter 3 will discuss about the project methodology used in this project such as calculation, simulation, fabrication and testing. All these methodology should be followed for a better performance.

Chapter 4, describe about the discussion and project finding such as the result and analysis. The result is presented by calculation. All the initial simulation results of planar couple microstrip line and collected data are documented using the table and discussed it. This is including the graphs that have obtained during the simulation.

Chapter five describe about expected result and the comparison results between simulation and measurement.

Finally the conclusion has been made and recommendation for the future works. The recommendation is added to give an opinion and also an improvement on how the future works should have done.

CHAPTER II

LITERATURE REVIEW

2.1 Introduction

This chapter gives a literature review and information relating to the microstrip design with the basic information related to this project and the design formulas for calculating.

2.2 Microstrip Line

2.2.1 Basic Microstrip Line

The microstrip line is most commonly used as microwave integrated circuit transmission medium. Microstrip transmission line is a kind of "high grade" printed circuit construction, consisting of a track of copper or other conductor on an insulating substrate. There is a "backplane" on the other side of the insulating substrate, formed from a similar conductor. Basically, it comprised of a metal strip supported above a larger dielectric material and a ground plane. Looking at the cross-section of the

microstrip transmission line, the track on top of the substrate will serve as a "hot" conductor, whereas the backplane on the bottom serves as a "return" conductor. Microstrip can therefore be considered a variant of a two wire transmission line [1].

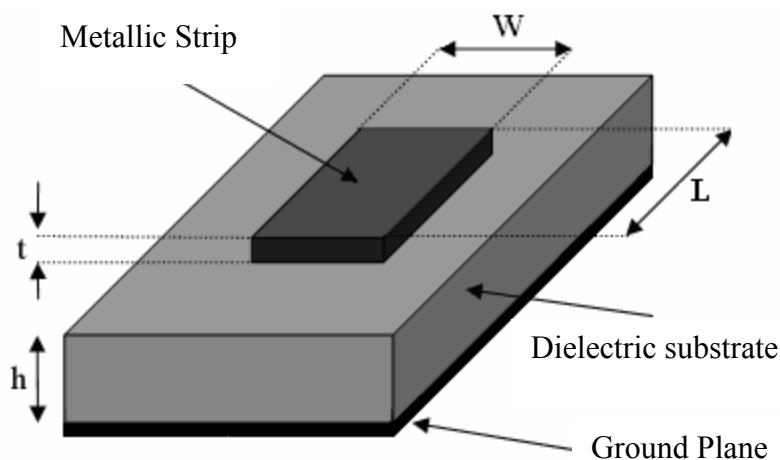


Figure 2.2.1: Structure of Microstrip Configuration [1]

The general geometry of microstrip is shown in figure 2.2.1 as above. The most important dimensional parameters in microstrip circuit design are the width w and height h (equivalent to the thickness of the substrate). Another important parameter is the relative permittivity of the substrate (ϵ_r). The thickness of the metallic, top conducting strip t and conductivity s are generally of much lesser importance and may be often neglected. The metallic strip is usually printed on a microwave substrate material.

2.2.2 Microstrip Field Radiation

If one solves the electromagnetic equations to find the field distributions, one will tend to find very nearly a completely TEM (transverse electromagnetic) pattern. This means that there are only a few regions in which there is a component of electric or magnetic field in the direction of wave propagation. The field pattern is commonly referred to as a Quasi-TEM pattern. Shown in figure 2.2.2 is the electromagnetic field pattern of the basic microstrip transmission line.

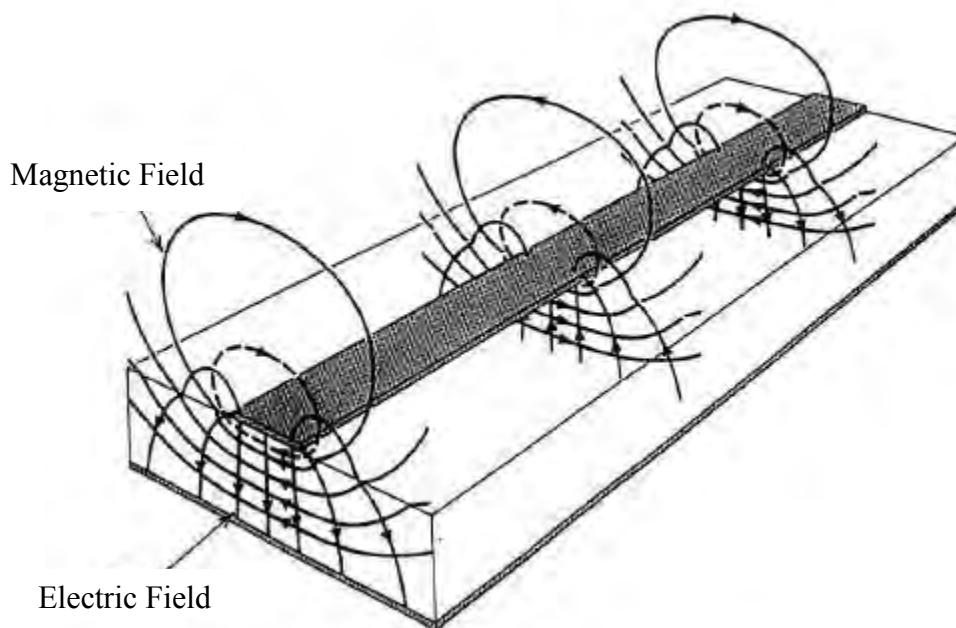


Figure 2.2.2: Electromagnetic Field Pattern of a Microstrip[1]

Under some conditions, one has to take into account of the effects due to longitudinal fields. An example is geometrical dispersion, where different wave frequencies travel at different phase velocities, and the group and phase velocities are different. The difference between microstrip transmission line and stripline is that the microstrip is a homogenous transmission line. This means that the electromagnetic fields are not entirely contained in the substrate. Hence, microstrip line cannot support pure TEM mode of transmission, as phase velocities would be different in the air and the substrate. Instead, a quasi-TEM mode is established. The quasi-TEM pattern arises because of the interface between the dielectric substrate and the surrounding air. The electric field lines have a discontinuity in direction at the interface. The boundary conditions for electric field are that the normal component (i.e. the component at right angles to the surface) of the electric field times the dielectric constant is continuous across the boundary; thus in the dielectric which may have dielectric constant 10, the electric field suddenly drops to 1/10 of its value in air. On the other hand, the tangential component (parallel to the interface) of the electric field is continuous across the boundary. In general, a sudden change of direction of electric field lines at the interface

is observed, which gives rise to a longitudinal magnetic field component from the second Maxwell's equation, $\text{curl } E = - dB/dt$. Since some of the electric energy is stored in the air and some in the dielectric, the effective dielectric constant for the waves on the transmission line will lie somewhere between that of the air and that of the dielectric. Typically the effective dielectric constant will be 50-85% of the substrate dielectric constant. Since the microstrip structure is not uniform, it will support the quasi-TEM mode [2].

2.2.3 Substrate Materials

The choice of substrate used is an important factor in the design of a microstrip filter. Important qualities of the dielectric substrate include [3]:

- i. The microwave dielectric constant
- ii. The frequency dependence of this dielectric constant which gives rise to "material dispersion" in which the wave velocity is frequency-dependent
- iii. The surface finish and flatness
- iv. The dielectric loss tangent, or imaginary part of the dielectric constant, which sets the dielectric loss
- v. The cost
- vi. The thermal expansion and conductivity
- vii. The dimensional stability with time
- viii. The surface adhesion properties for the conductor coatings
- ix. The manufacturability (ease of cutting, shaping, and drilling)
- x. The porosity (for high vacuum applications)

Since the substrate dimensions and dielectric constant are functions of substrate temperature, the operating temperature range becomes an important property in the design of any microstrip filter. In addition, the dielectric constant and loss tangent are also functions of frequency. As for a physical property which is important in fabrication

of the filter, they are resistance to chemicals, tensile and structural strengths, flexibility, machinability, impact resistance, strain relief, formability, bondability and substrate characteristics when clad. Generally, there are two types of substrates used: soft and hard substrates [2]. Soft substrates are flexible, cheap and can be fabricated easily. However, it possesses higher thermal expansion coefficients. Typical examples of soft substrates are RT Duriod 5870 ($\epsilon_r = 2.3$), RT Duriod 5880 ($\epsilon_r = 2.2$) and RT Duriod 6010.5 ($\epsilon_r = 10.5$). As for hard substrates, it has better reliability and lower thermal expansion coefficients. On the other hand, it is more expensive and non-flexible. Typical examples of hard substrates are quartz ($\epsilon_r = 3.8$), alumina ($\epsilon_r = 9.7$), sapphire ($\epsilon_r = 11.7$) and Gallium Arsenide GaAs ($\epsilon_r = 12.3$).

Normally, thick substrates with low dielectric constants are often used as it provides better efficiency, larger bandwidth and loosely bound fields for radiation into space. However, it would also result in a larger filter size. On the other hand, using thin substrates with higher dielectric constants would result in smaller filter size. The drawbacks are that it is less efficient and has relatively smaller bandwidths. Therefore, there must be a design trade-off between the filter size and good filter performance.

2.2.4 Applications

Due to the fact that most present-day systems demand for small size, lightweight and low cost the employment of microstrip technology arises extensively over the years. Microstrip are particularly suited to those applications where low profile because it can conform to a given shape easily. Shown below are some typical system applications which employ microstrip technology [8]:

- i. Satellite communications
- ii. Doppler and other radars
- iii. Radio altimeter
- iv. Command and control